Internally Matched Power GaAs FETs (C-Band)

Features

- High power
 - P_{1dB} = 36.0 dBm at 6.4 GHz to 7.2 GHz
- High gain
- $G_{1dB} = 8.5 \text{ dB}$ at 6.4 GHz to 7.2 GHz Broad band internally matched
- · Hermetically sealed package

RF Performance Specifications ($T_a = 25^{\circ} C$)

| Characteristics | Symbol | Condition | Unit | Min. | Тур. | Мах |
|------------------------------------------|------------------|---------------------------------------------------------|------|------|------|-----|
| Output Power at 1dB Compression Point | P _{1dB} | | dBm | 35.0 | 36.0 | - |
| Power Gain at 1dB Compression Point | G _{1dB} | V _{DS} = 10V f = 6.4 ~ 7.2 GHz | dB | 7.0 | 8.0 | - |
| Drain Current | I _{DS} | | А | _ | 1.1 | 1.5 |
| Power Added Efficiency | η_{add} | | % | _ | 30 | - |
| Channel-Temperature Rise | ΔT_{ch} | V _{DS} xI _{DS} xR _{th} (c-c) | °C | - | _ | 80 |

Electrical Characteristics ($T_a = 25^{\circ} C$)

| Characteristic | Symbol | Condition | Unit | Min. | Тур. | Мах |
|----------------------------------|-----------------------|------------------------------------------------|------|------|------|-----|
| Trans-conductance | gm | V _{DS} = 3V I _{DS} = 1.5A | mS | _ | 900 | - |
| Pinch-off Voltage | V _{GSoff} | $V_{DS} = 3V$ $I_{DS} = 20mA$ | V | -2 | -3.5 | -5 |
| Saturated Drain Current | I _{DSS} | $V_{DS} = 3V$ $V_{GS} = 0V$ | А | _ | 2.9 | 3.8 |
| Gate to Source Breakdown Voltage | V _{GSO} | I _{GS} = -60 μA | V | -5 | _ | _ |
| Thermal Resistance | R _{th (c-c)} | Channel to case | °C/W | _ | 4.0 | 6.0 |

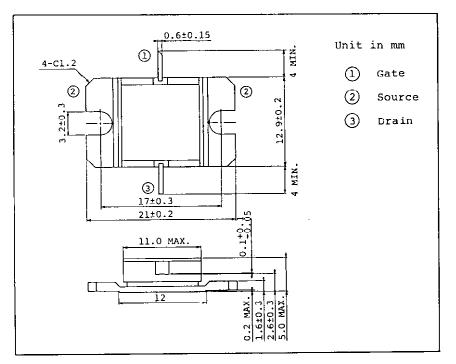
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Absolute Maximum Ratings (Ta = 25° C)

| Characteristic | Symbol | Unit | Rating |
|-------------------------------------|------------------|------|---------|
| Drain Source Voltage | V _{DS} | V | 15 |
| Gate Source Voltage | V _{GS} | V | -5 |
| Drain Current | ۱ _D | А | 4 |
| Total Power Dissipation (Tc = 25°C) | P _T | W | 20 |
| Channel Temperature | T _{ch} | °C | 175 |
| Storage Temperature | T _{stg} | °C | -65~175 |

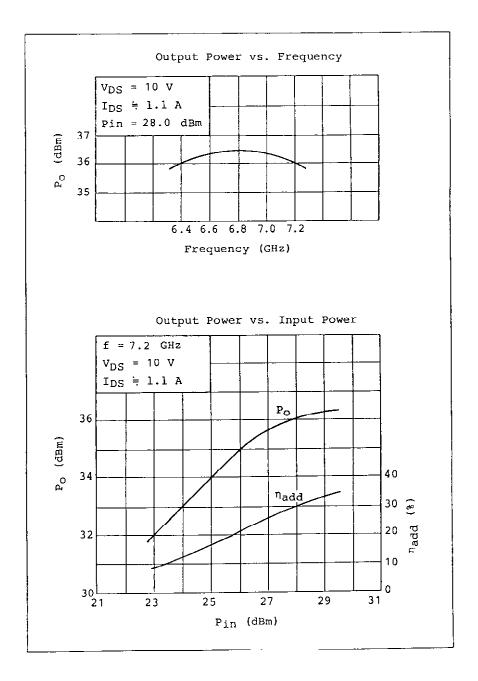
Package Outline (2-11D1B)



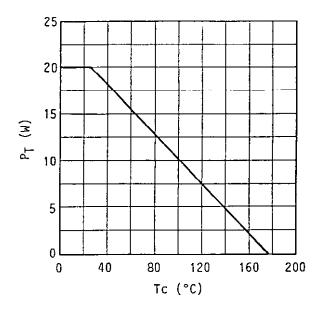
Handling Precautions for Packaged Type

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

RF Performances



Power Dissipation vs. Case Temperature



TIM6472-4 S-Parameters (MAGN. and ANGLES)

